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IC Packages, Assembly & Prototype Services

Press Release

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Quik-Pak Announces New BGA Service

SAN DIEGO, April 11 -- Quik-Pak, a division of Delphon Industries and leader in quick-turn integrated circuit (IC) prototype packaging, has announced the installation of a new process line for Ball Grid Array(BGA)sphere attach. Quik-Pak offers initial BGA balling services, as well as rework of existing substrates, with SnPb or Pb-free sphere sizes ranging from 0.010″ to 0.030″ in diameter. The new in-house capability complements Quik-Pak's existing rapid turn IC assembly service offerings, which include die bonding, gold ball wire bonding, remolding and marking/branding. Quik-Pak is also the largest supplier of open cavity plastic packages, which allow IC designers to insert new die in existing production packages for design verification, testing and customer samples.

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Background:

Quik-Pak, a division of Delphon Industries, offers IC packages, assembly and prototype services. The company specializes in open-cavity plastic packages and assembly in 24 hours or less. A limitless array of open-cavity packages is available with no minimum quantity and can be provided as part of a turn-key assembly solution along with wafer dicing, die/wire bonding, remolding and marking/branding. Custom assembly services are also offered for ceramic packages, chip-on-board, stacked die, MEMS, etc. Quik-Pak's unique offerings deliver faster time to market and reduced prototype costs for new devices, while providing excellent flexibility, quality and customer service.

For further information, contact Quik-Pak, 10987 Via Frontera, San Diego, CA 92127, phone 1(858)674-4676,moreinfo@icproto.com.

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